

AG-1 {A,B} manufacturing specification

Material: Rogers 3003

Glass weave style: 3313 MS

Board thickness: 1.00 ± 0.10 mm (recommend 0.9mm)

*Card thickness applies across tabs and includes plating and/or metallization.

Dimensions: 50.95mm x 30mm – follow exact requirements of miniPCle spec.

Layers: 8

Copper: 1oz

Surface finishing: ENIG Ni: 6um Au: 0.1um

Solder mask: white

Silkscreen: bright orange color

Request golden finger miniPCle contacts Ni: 2um Au: 1um

Edge bevel: 0.25mm, 45-degrees, both sides.

Layer stack up;

PolysomeCrypto01.GTL

PolysomeCrypto01.G1

PolysomeCrypto01.G2

PolysomeCrypto01.G3

PolysomeCrypto01.G4

PolysomeCrypto01.G5

PolysomeCrypto01.G6

PolysomeCrypto01.GBL

Impedance matching at 50R on all the 5 mil traces for;

PolysomeCrypto01.GTL

PolysomeCrypto01.G3

PolysomeCrypto01.G5

PolysomeCrypto01.GBL

